

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSP 60 H6327	**Issued**	02. June 2021
MA#	MA001219564		
Package	PG-SOT223-4-24	**Weight***	107.18 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.003			27	
	noble metal	gold	7440-57-5	0.011	0.01		105	
	inorganic material	silicon	7440-21-3	0.137	0.13	0.14	1278	1410
leadframe	inorganic material	silicon	7440-21-3	0.009	0.01		80	
	non noble metal	titanium	7440-32-6	0.043	0.04		398	
	non noble metal	chromium	7440-47-3	0.128	0.12		1193	
	non noble metal	copper	7440-50-8	42.459	39.61	39.78	396141	397812
wire	non noble metal	copper	7440-50-8	0.082	0.08	0.08	766	766
encapsulation	organic material	carbon black	1333-86-4	0.624	0.58		5817	
	plastics	epoxy resin	-	9.353	8.73		87261	
	inorganic material	silicondioxide	60676-86-0	52.375	48.86	58.17	488660	581738
leadfinish	non noble metal	tin	7440-31-5	1.464	1.37	1.37	13659	13659
plating	noble metal	silver	7440-22-4	0.495	0.46	0.46	4615	4615
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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